



Material Content Data Sheet



Sales Product Name		IPB123N10N3 G		Issued		29. August 2013		
MA#		MA000803294						
Package		PG-TO263-3-2		Weight*		1462.85 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.094	0.21	0.21	2115	2115
leadframe	non noble metal	iron	7439-89-6	0.853	0.06		583	
	inorganic material	phosphorus	7723-14-0	0.256	0.02		175	
	non noble metal	copper	7440-50-8	851.691	58.22	58.30	582216	582974
wire	non noble metal	aluminium	7429-90-5	7.261	0.50	0.50	4963	4963
encapsulation	organic material	carbon black	1333-86-4	8.803	0.60		6018	
	plastics	epoxy resin	-	96.836	6.62		66197	
	inorganic material	silicondioxide	60676-86-0	481.248	32.90	40.12	328981	401196
leadfinish	non noble metal	tin	7440-31-5	9.657	0.66	0.66	6601	6601
plating	non noble metal	nickel	7440-02-0	0.228	0.02		156	
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.02	0	156
solder	noble metal	silver	7440-22-4	0.073	0.00		50	
	non noble metal	tin	7440-31-5	0.058	0.00		40	
	non noble metal	lead	7439-92-1	2.787	0.19	0.19	1905	1995
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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